

FEATURES

- Operates from a Single 3.3V Supply
- Low Supply Current: $I_{CC} = 200\mu A$
- $I_{CC} = 35\mu A$ in Driver Disable Mode
- $I_{CC} = 0.2\mu A$ in Shutdown Mode
- ESD Protection Over $\pm 10kV$
- Uses Small Capacitors: $0.1\mu F$
- Operates to 120kBaud
- Output Overvoltage Does Not Force Current Back into Supplies
- EIA/TIA-562 I/O Lines Can Be Forced to $\pm 25V$ Without Damage
- Pin Compatible with LT1180A

APPLICATIONS

- Notebook Computers
- Palmtop Computers

DESCRIPTION

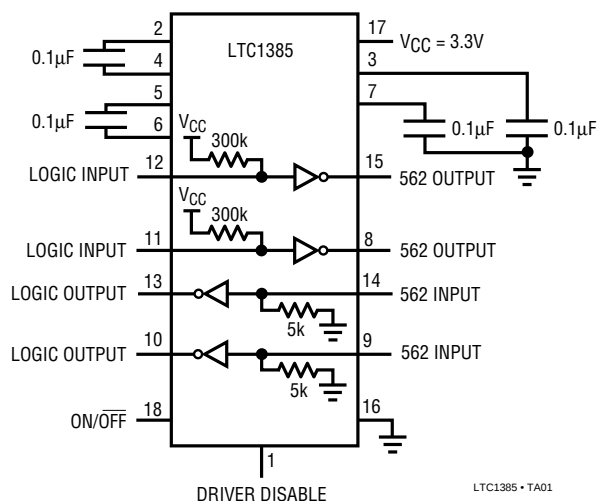
The LTC1385 is an ultra-low power, 2-driver/2-receiver EIA/TIA-562 transceiver which operates from a single 3.3V supply. The charge pump requires only four space-saving $0.1\mu F$ capacitors.

The transceiver operates in one of three modes: Normal, Driver Disable or Shutdown. In the Normal mode, I_{CC} is only $200\mu A$ in the unloaded condition. In the Driver Disable mode, the charge pump is turned off, the driver outputs are forced into three-state, both receivers are kept active, and I_{CC} drops to $35\mu A$. In the Shutdown mode, everything is turned off and I_{CC} drops to $0.2\mu A$.

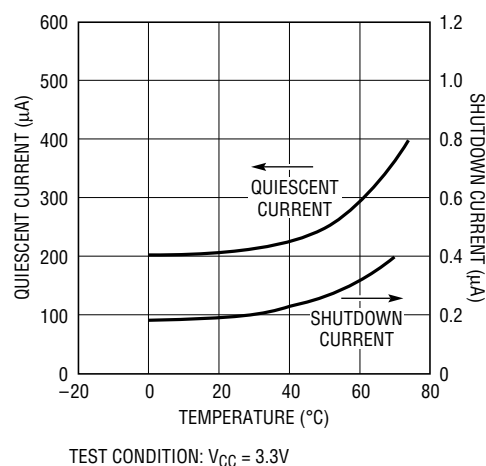
The LTC1385 is fully compliant with all data rate and overvoltage EIA/TIA-562 specifications. The transceiver can operate up to 120kbaud with a $1000pF$, $3k\Omega$ load. Both driver outputs and receiver inputs can be forced to $\pm 25V$ without damage, and can survive multiple $\pm 10kV$ ESD strikes.

TYPICAL APPLICATION

**2-Drivers/2-Receivers with Shutdown
and Driver Disable**



**Quiescent and Shutdown Supply Current
vs Temperature**



LTC1385 • TA02

ABSOLUTE MAXIMUM RATINGS

Supply Voltage (V_{CC})	5V	Short-Circuit Duration	
Input Voltage		V^+	30 sec
Driver	$-0.3V$ to $V_{CC} + 0.3V$	V^-	30 sec
Receiver	$-25V$ to $25V$	Driver Output	Indefinite
Digital Input	$-0.3V$ to $V_{CC} + 0.3V$	Receiver Output	Indefinite
Output Voltage		Operating Temperature Range	$0^{\circ}C$ to $70^{\circ}C$
Driver	$-25V$ to $25V$	Storage Temperature Range	$-65^{\circ}C$ to $150^{\circ}C$
Receiver	$-0.3V$ to $V_{CC} + 0.3V$	Lead Temperature (Soldering, 10 sec)	$300^{\circ}C$

PACKAGE/ORDER INFORMATION

TOP VIEW	ORDER PART NUMBER	TOP VIEW	ORDER PART NUMBER
DRIVER DISABLE 1, C1⁺ 2, V⁺ 3, C1⁻ 4, C2⁺ 5, C2⁻ 6, V⁻ 7, TR2 OUT 8, RX2 IN 9, NC 10, ON/OFF 20, VCC 19, GND 18, TR1 OUT 17, RX1 IN 16, RX1 OUT 15, TR1 IN 14, TR2 IN 13, RX2 OUT 12, NC 11 G PACKAGE 20-LEAD SSOP $T_{JMAX} = 125^{\circ}C$, $\theta_{JA} = 135^{\circ}C/W$	LTC1385CG	DRIVER DISABLE 1, C1⁺ 2, V⁺ 3, C1⁻ 4, C2⁺ 5, C2⁻ 6, V⁻ 7, TR2 OUT 8, RX2 IN 9, ON/OFF 18, VCC 17, GND 16, TR1 OUT 15, RX1 IN 14, RX1 OUT 13, TR1 IN 12, TR2 IN 11, RX2 OUT 10 N PACKAGE 18-LEAD PLASTIC DIP S PACKAGE 18-LEAD PLASTIC SOL $T_{JMAX} = 125^{\circ}C$, $\theta_{JA} = 85^{\circ}C/W$	LTC1385CN LTC1385CS

Consult factory for Industrial and Military grade parts.

DC ELECTRICAL CHARACTERISTICS

$V_{CC} = 3.3V$, $C1 = C2 = C3 = C4 = 0.1\mu F$, $V_{ON/OFF} = V_{CC}$, Driver Disable = V_{CC} , unless otherwise noted.

PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
Any Driver					
Output Voltage Swing	3k to GND	3.7	4.5		V
	Positive	•			V
Logic Input Voltage Level	Input Low Level ($V_{OUT} = \text{High}$)	•	1.4	0.8	V
	Input High Level ($V_{OUT} = \text{Low}$)	•	2.0	1.4	V
Logic Input Current	$V_{IN} = V_{CC}$	•		5	μA
	$V_{IN} = 0V$	•	-20	-40	μA
Output Short-Circuit Current	$V_{OUT} = 0V$		± 10		mA
Output Leakage Current	Shutdown or Driver Disable or $V_{CC} = 0V$ (Note 3,4), $V_{OUT} = \pm 20V$	•	± 10	± 500	μA

DC ELECTRICAL CHARACTERISTICS

$V_{CC} = 3.3V$, $C1 = C2 = C3 = C4 = 0.1\mu F$, $V_{ON/OFF} = V_{CC}$, Driver Disable = V_{CC} , unless otherwise noted.

PARAMETER	CONDITIONS		MIN	TYP	MAX	UNITS
Any Receiver						
Input Voltage Thresholds	Input Low Threshold	●	0.8	1.3		V
	Input High Threshold	●		1.7	2.4	V
Hysteresis		●	0.1	0.4	1.0	V
Input Resistance	$-10V \leq V_{IN} \leq 10V$		3	5	7	k Ω
Output Voltage	Output Low, $I_{OUT} = -1.6mA$ ($V_{CC} = 3.3V$)	●		0.2	0.4	V
	Output High, $I_{OUT} = 160\mu A$ ($V_{CC} = 3.3V$)	●	3.0	3.2		V
Output Short-Circuit Current	Sinking Current, $V_{OUT} = V_{CC}$		-5	-20		mA
	Sourcing Current, $V_{OUT} = 0V$		2	7		mA
Output Leakage Current	Shutdown (Note 4), $0V \leq V_{OUT} \leq V_{CC}$	●		1	10	μA
Power Supply Generator						
V^+ Output Voltage	$I_{OUT} = 0mA$			5.7		V
	$I_{OUT} = 5mA$			5.5		V
V^- Output Voltage	$I_{OUT} = 0mA$			-5.3		V
	$I_{OUT} = -5mA$			-5.0		V
Supply Rise Time	Shutdown or Driver Disable to Turn-On			0.2		ms
Power Supply						
V_{CC} Supply Current	No Load (Note 2)	●		0.2	0.5	mA
Supply Leakage Current (V_{CC})	Shutdown (Note 4)	●		0.2	10	μA
	Driver Disable (Note 3)	●		35	50	μA
Digital Input Threshold Low		●		1.4	0.8	V
Digital Input Threshold High		●	2.0	1.4		V

AC CHARACTERISTICS

$V_{CC} = 3.3V$, $C1 = C2 = C3 = C4 = 0.1\mu F$, unless otherwise noted.

PARAMETER	CONDITIONS		MIN	TYP	MAX	UNITS
Slew Rate	$R_L = 3k$, $C_L = 51pF$			8	30	V/ μs
	$R_L = 3k$, $C_L = 1000pF$		3	5		V/ μs
Driver Propagation Delay (TTL to EIA/TIA-562)	t_{HLD} (Figure 1)	●		2	3.5	μs
	t_{LHD} (Figure 1)	●		2	3.5	μs
Receiver Propagation Delay (EIA/TIA-562 to TTL)	t_{HLR} (Figure 2)	●		0.3	0.8	μs
	t_{LHR} (Figure 2)	●		0.2	0.8	μs

The ● denotes specifications which apply over the operating temperature range $0^\circ C \leq T_A \leq 70^\circ C$.

Note 1: Absolute maximum ratings are those values beyond which the life of the device may be impaired.

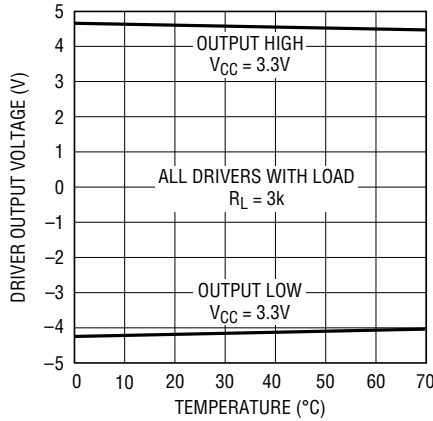
Note 2: Supply current is measured with driver and receiver outputs unloaded.

Note 3: Measurements made in the Driver Disable mode are performed with $V_{DRIVER\ DISABLE} = GND$ and $V_{ON/OFF} = V_{CC}$.

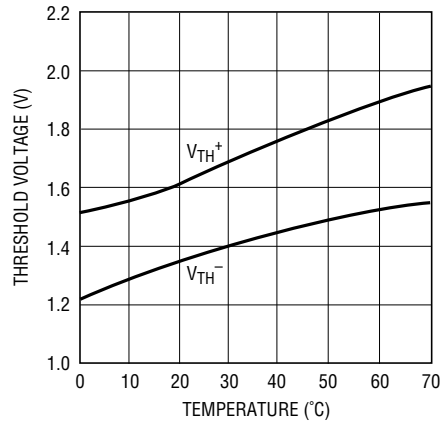
Note 4: Measurements made in the Shutdown mode are performed with $V_{ON/OFF} = 0V$.

TYPICAL PERFORMANCE CHARACTERISTICS

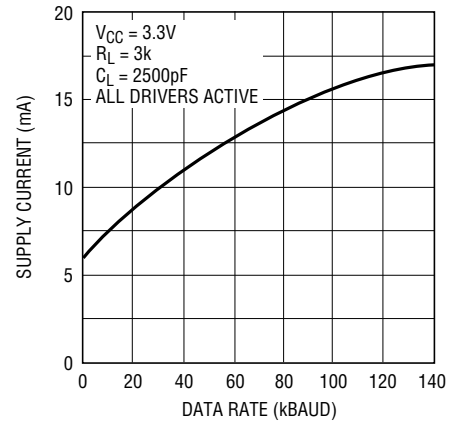
Driver Output Voltage vs Temperature



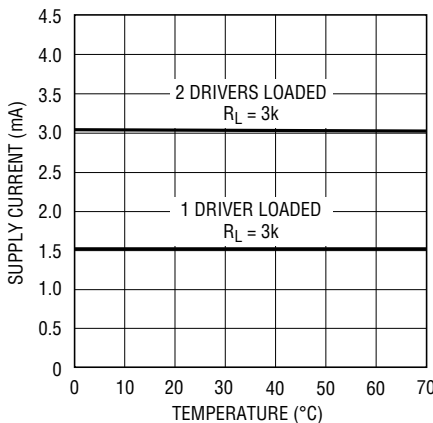
Receiver Input Thresholds vs Temperature



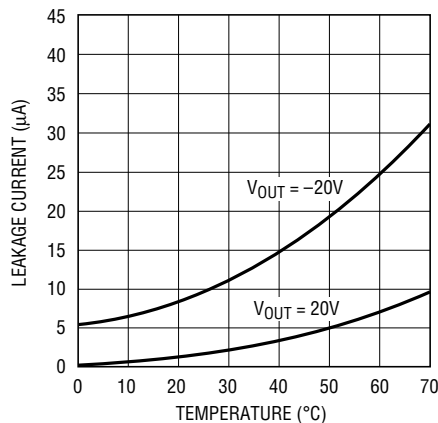
Supply Current vs Data Rate



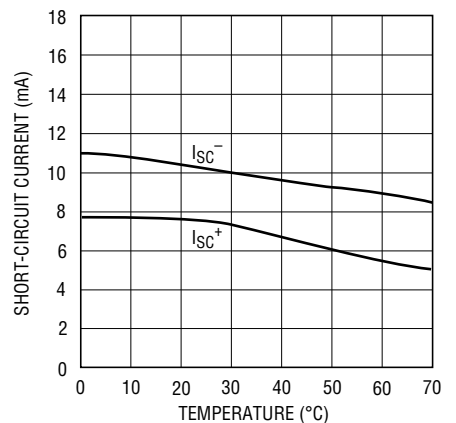
V_{CC} Supply Current vs Temperature



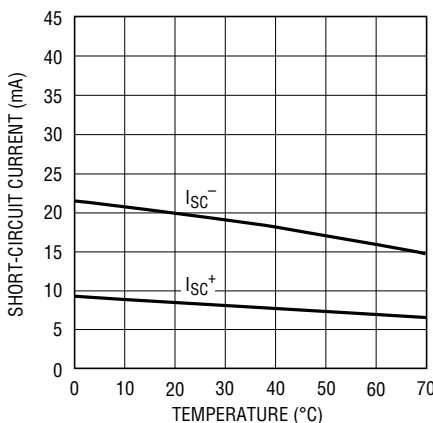
Driver Leakage in Shutdown vs Temperature



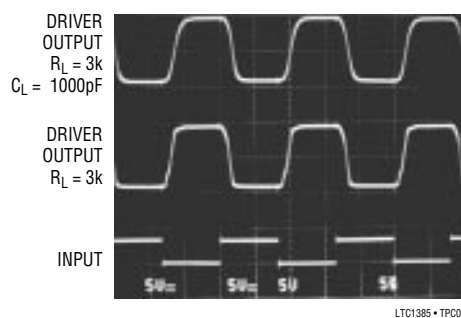
Driver Short-Circuit Current vs Temperature



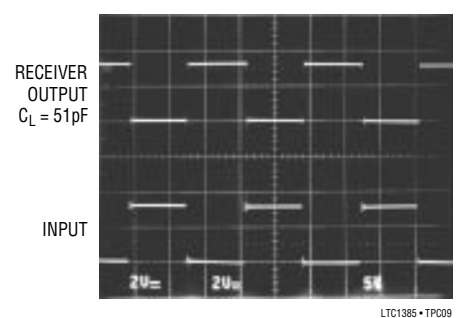
Receiver Short-Circuit Current vs Temperature



Driver Output Waveforms



Receiver Output Waveform



PIN FUNCTIONS

V_{CC}: 3.3V Input Supply Pin. This pin should be decoupled with a 0.1μF ceramic capacitor.

GND: Ground Pin.

ON/OFF: TTL/CMOS Compatible Shutdown Pin. A logic low puts the device in the Shutdown mode independent of the Driver Disable pin. The supply current drops to 0.2μA and all driver and receiver outputs are forced into three-state.

DRIVER DISABLE: TTL/CMOS Compatible Input Pin. With the ON/OFF pin held high, a logic low forces the part into the Driver Disable mode with the charge pump turned off and the driver outputs forced into three-state. Both receivers remain active and the supply current drops to 35μA. A logic high forces the part into the Normal mode.

V⁺: Positive Supply Output (EIA/TIA-562 Drivers). $V^+ \cong 2V_{CC} - 1V$. This pin requires an external capacitor $C = 0.1\mu F$ for charge storage. The capacitor may be tied to ground or V_{CC} . With multiple devices, the V^+ and V^- pins may share a common capacitor. For a large number of devices, increasing the size of the shared common storage capacitors is recommended to reduce ripple.

V⁻: Negative Supply Output (EIA/TIA-562 Drivers). $V^- \cong -(2V_{CC} - 1.3V)$. This pin requires an external capacitor $C = 0.1\mu F$ for charge storage.

C1⁺, C1⁻, C2⁺, C2⁻: Commutating Capacitor Inputs. These pins require two external capacitors $C = 0.1\mu F$: one from C1⁺ to C1⁻, and another from C2⁺ to C2⁻. To maintain charge pump efficiency, the capacitor's effective series resistance should be less than 2Ω.

TR IN: EIA/TIA-562 Driver Input Pins. Inputs are TTL/CMOS compatible. The inputs of unused drivers can be left unconnected since 300k input pull-up resistors to V_{CC} are included on chip. To minimize power consumption, the internal driver pull-up resistors are disconnected from V_{CC} in the Shutdown mode.

TR OUT: Driver Outputs at EIA/TIA-562 Voltage Levels. Outputs are in a high impedance state when in the Shutdown or Driver Disable mode or $V_{CC} = 0V$. The driver outputs are protected against ESD to ±10kV for human body model discharges.

RX IN: Receiver Inputs. These pins can be forced to ±25V without damage. The receiver inputs are protected against ESD to ±10kV for human body model discharges. Each receiver provides 0.4V of hysteresis for noise immunity.

RX OUT: Receiver Outputs with TTL/CMOS Voltage Levels. Outputs are in a high impedance state when in the Shutdown mode.

SWITCHING TIME WAVEFORMS

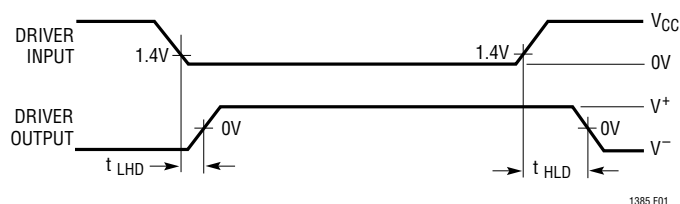


Figure 1. Driver Propagation Delay Timing

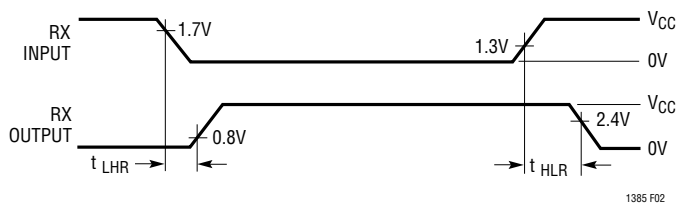
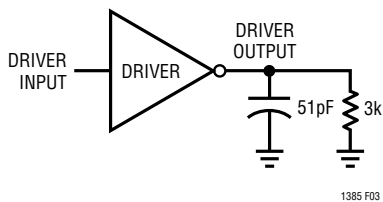


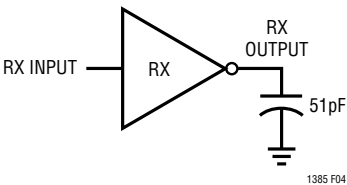
Figure 2. Receiver Propagation Delay Timing

TEST CIRCUITS

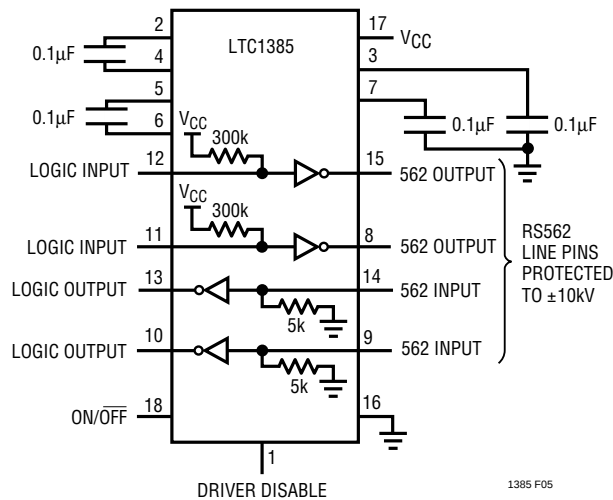
Driver Timing Test Load



Receiver Timing Test Load



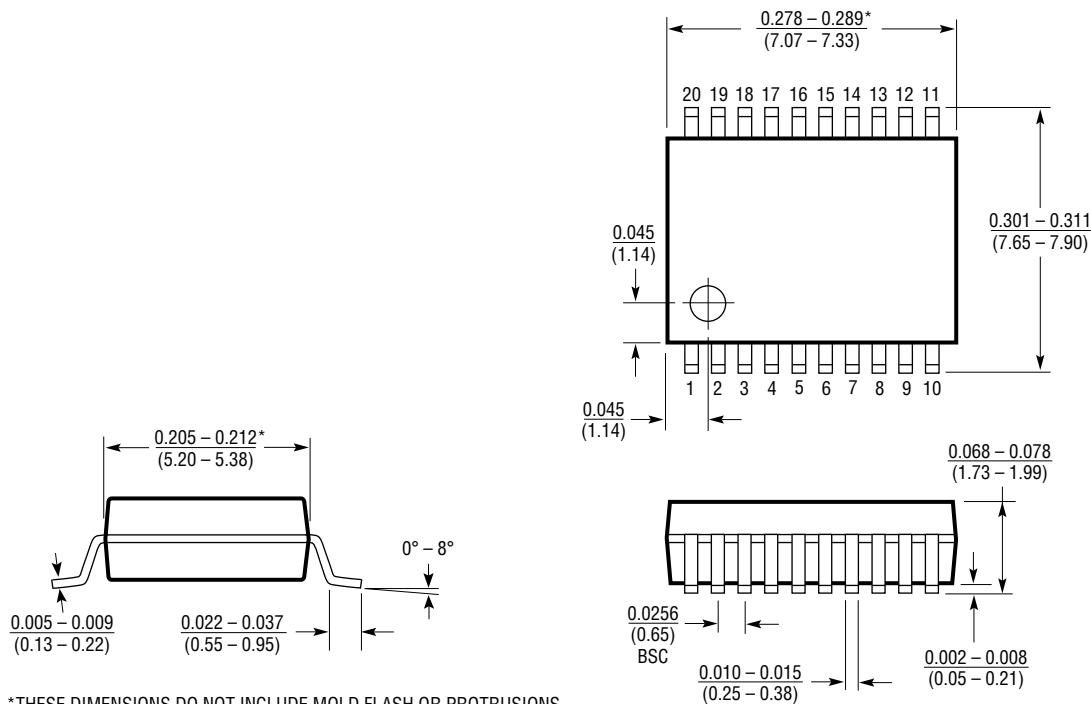
ESD Test Circuit



PACKAGE DESCRIPTION

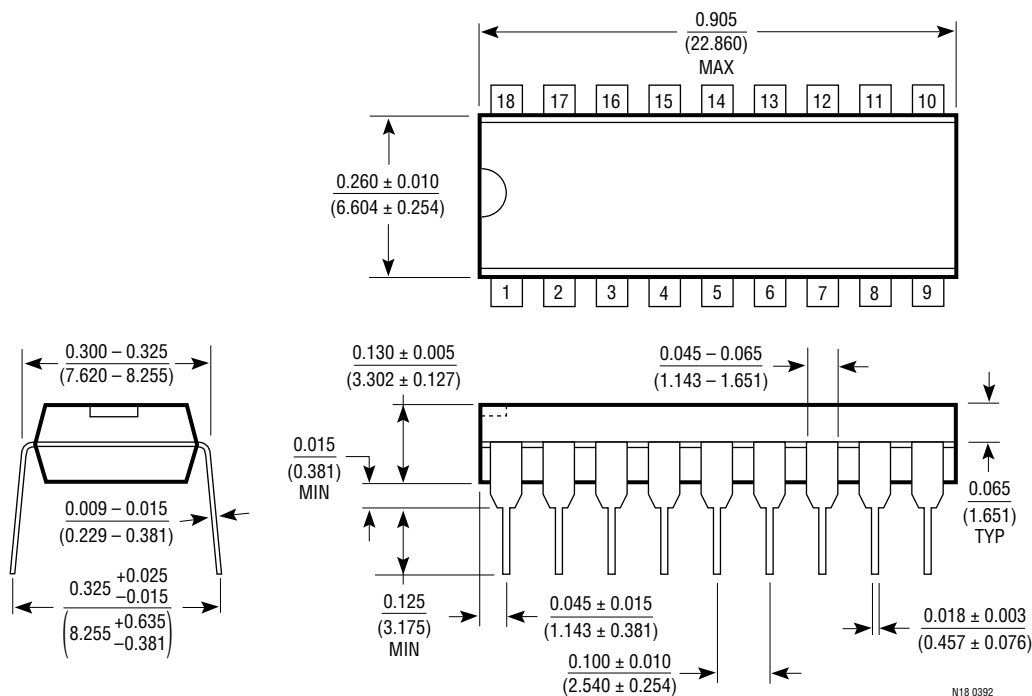
Dimensions in inches (millimeters) unless otherwise noted.

G Package 20-Lead SSOP



20SSOP 0294

N Package 18-Lead Plastic DIP

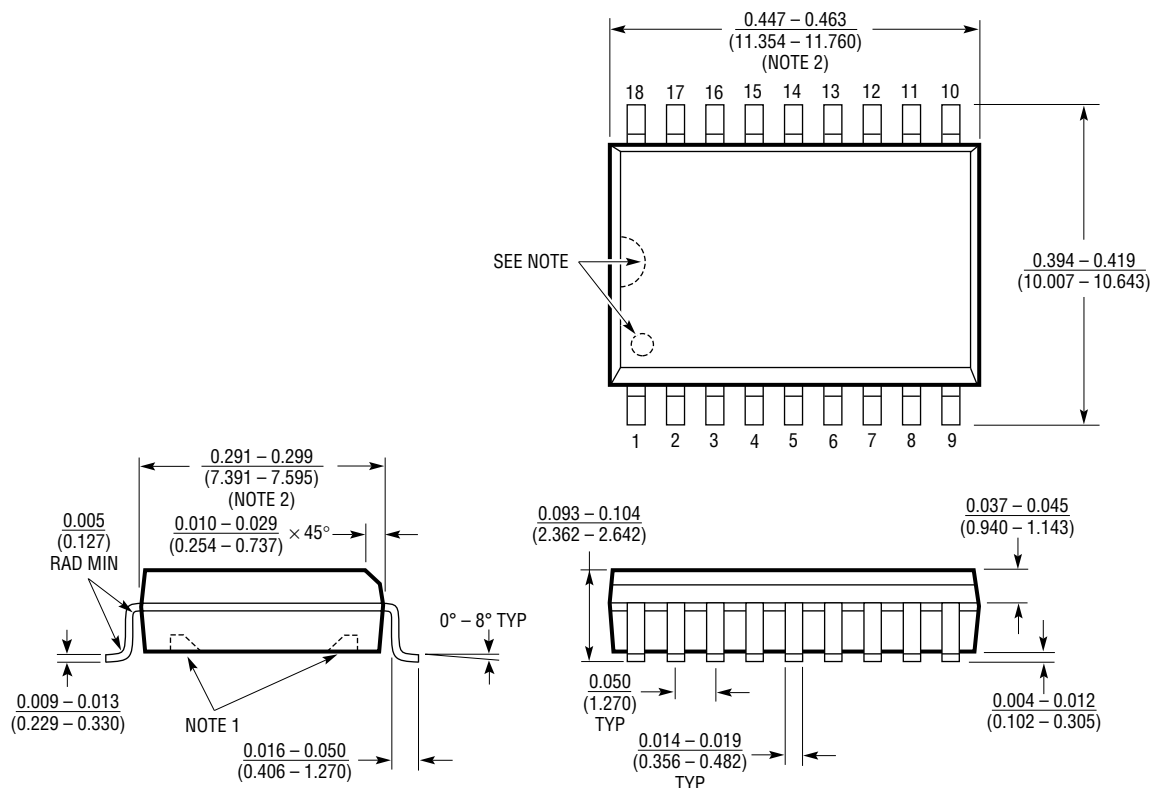


N18 0392

PACKAGE DESCRIPTION

Dimensions in inches (millimeters) unless otherwise noted.

S Package 18-Lead Plastic SOL



NOTE:

- PIN 1 IDENT, NOTCH ON TOP AND CAVITIES ON THE BOTTOM OF PACKAGES ARE THE MANUFACTURING OPTIONS. THE PART MAY BE SUPPLIED WITH OR WITHOUT ANY OF THE OPTIONS.
- THESE DIMENSIONS DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.006 INCH (0.15mm).

SOL18 0392